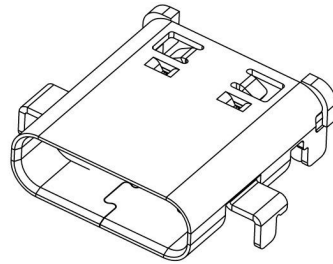
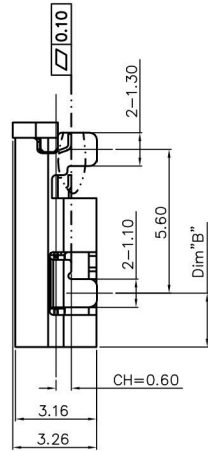
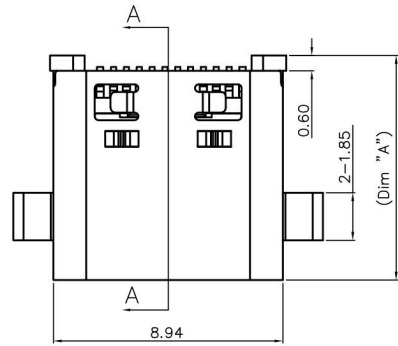
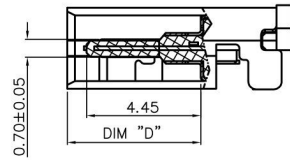
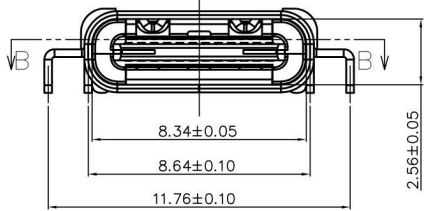
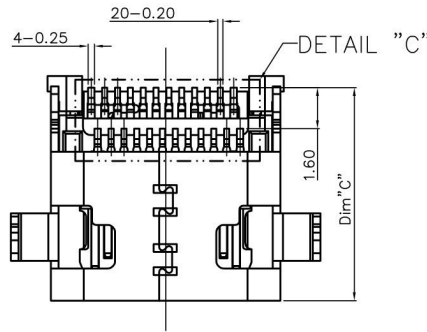


REV	ECN NO.	DISCRIPTION	CHEKED/DATE	APPD/DATE

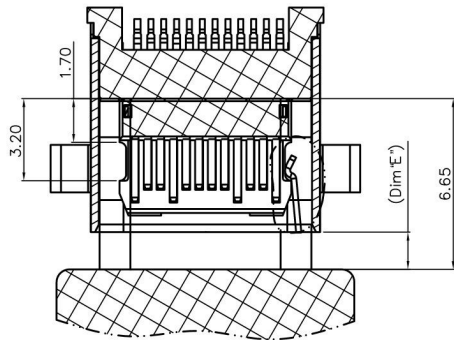


- NOTES:
- MATERIAL:
 - MOLDING: LCP UL94 V-0
 - CONTACT: COPPER ALLOY.
 - GOLD PLATED Min ON CONTACT AREA, 100u" Min TIN (LEAD FREE) ON SOLDER AREA,
 - SHELL: SUS304-H, T=0.30±0.03mm
 - 30u" NICKEL PLATING OVER ALL.
 - SHILD: SUS304-H, T=0.12±0.03mm
 - MECHANICAL:
 - INSERTION: 5~20N.
 - EXTRACTION: 8~20N AFTER TEST.
 - DURABILITY: 10000 CYCLES
 - ELECTRICAL:
 - CURRENT: 5A FOR VBUS;
 - 1.25A FOR GND PIN.
 - 0.25A FOR OTHER.
 - VOLTAGE: 20 V MAX
 - WITHSTANDING VOLTAGE: 100V AC R.M.S.
 - CONTACT RESISTANCE: 40mΩ MAX.
 - INSULATION RESISTANCE: 100MΩ MIN.
 - ENVIRONMENTAL
 - TEMPERATURE RANGE -25°C ~ +85°C

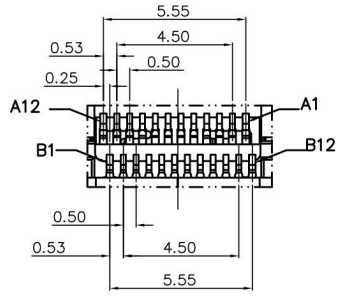


SECTION A-A

ITEM:USB3.1 TYPE-C 24PF-029



SECTION B-B
MATTING VIEW



DETAIL "C"

8.35	1.75	7.90	4.80	1.8
Dim "A"	Dim "B"	Dim "C"	Dim "D"	Dim "E"

RUI CHI

. X: ±0.25	X. : ±1°	APP.	DWG NO.	XWUC30037 (CU)
. XX: ±0.15	. X: ±0.5°	CHK.	TITLE	
. XXX: ±0.05	. XX: ±0.02°	DGN.	SERIES	
UNIT mm	SCALE 1:1	DRW.		
REV. A0	SHEET: 1/2			